

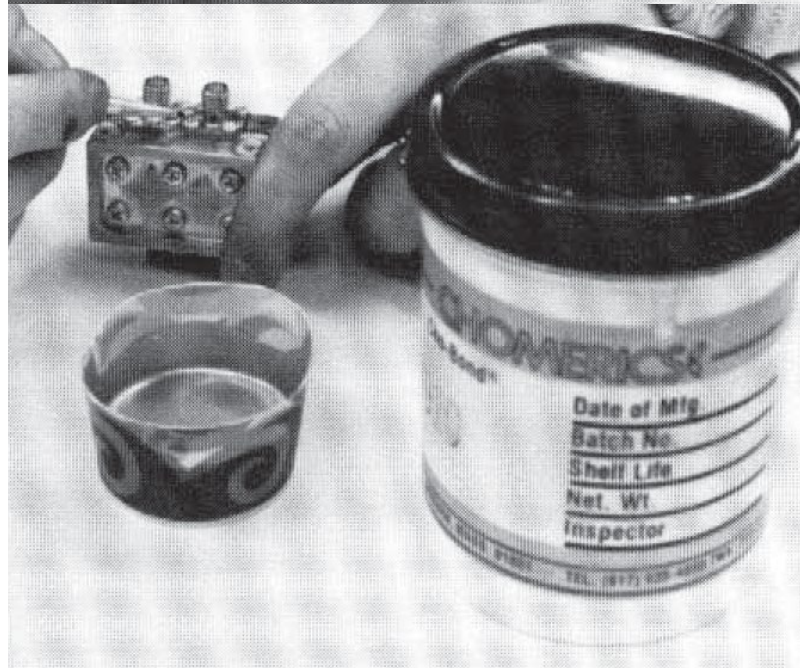
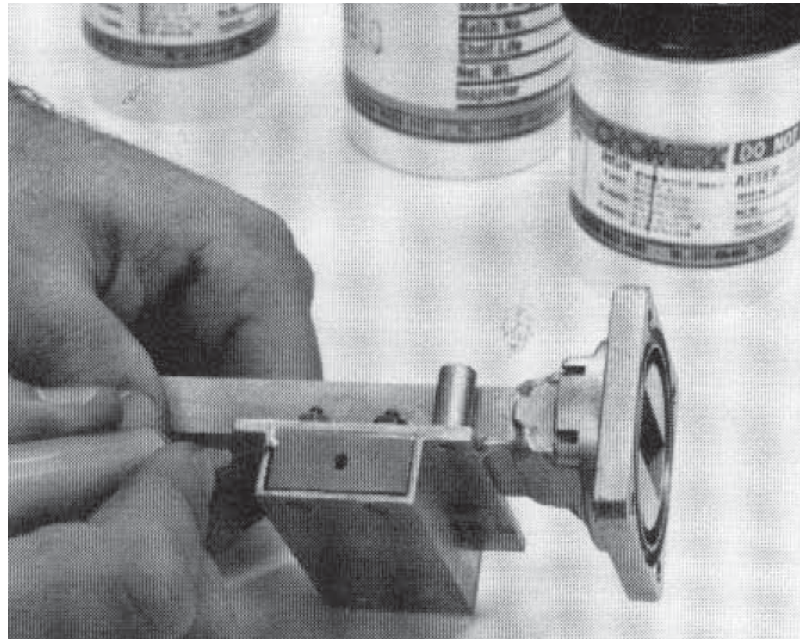
CHO-BOND® 592

Two Component Electrically Conductive Epoxy Adhesive System

CHO-BOND® 592 is a highly conductive silver-filled epoxy adhesive which combines the best properties of metals and organics. This two-component system is unique in that it combines long pot life, good electrical conductivity, excellent adhesion, low temperature cure, easy mix ratio, low viscosity, low coefficient of thermal expansion, very low thermal impedance and good thermal shock resistance. It may be thinned with toluene for spray application.

Product Features

- Connects dissimilar materials electrically and thermally
- Excels as a sealant for microwave modules and components
- Ideal for circuit board repair and grounding applications
- Useful for EMI shielding applications



CHO-BOND® 592 PRODUCT INFORMATION

Typical Properties	CHO-BOND 584-208	Test Method	
Specific Gravity	2.6 ± 0.25	ASTM D792	(Q/C)
Volume Resistivity	0.05 ohm-cm	N/A	
Pot Life	@25 °C (77 °F): 4-6 hrs @5 °C (41 °F) 48 hrs	N/A	
Shelf Life @ 25 °C (77 °F)	9 months	N/A	
Lap Shear Strength	1500 psi (105kg/cm ²)	N/A	
Mix Ratio, A : B (by weight)	100:50	N/A	
Curing Schedules	60 min @ 80 °C (176 °F) 30 min @ 100 °C (212 °F) 15 min @ 125 °C (257 °F) 5 min @ 150 °C (302 °F)	N/A	
Room Temperature Cure 25 °C (77 °F)	1 week*	N/A	

* CHO-BOND 592 may be cured at room temperature, but there will be a sacrifice in electrical conductivity.



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